

OPTO-ELECTRONIC DEVICES DIVISION ELECTRONIC COMPONENTS GROUP SHARP CORPORATION

### **SPECIFICATION**

PHOTOCO MODEL No.	UPLER.
PC41	OL
Business dealing name O PC410LENIP	Business dealing name PC410LEYIP
Specified for	
Enclosed please find copies of the Specifications of After confirmation of the contents, please be sure with approving signature on each.	which consists of 15 pages including cover. to send back copy of the Specifications
CUSTOMER'S APPROVAL	PRESENTED
CUSTOMER'S APPROVAL  DATE	PRESENTED  DATE 7 Nov. 2002
	TS A TETE

D	PHOTOCOUPLER	
Product name:	PHOTOCOUPLER	

Model No.: PC410L

Business dealing name	Business dealing name
PC410LENIP	PC410LEYIP

- 1. These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp"). Please do not reproduce or cause anyone to reproduce them without Sharp's consent.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) This product is designed for use in the following application areas;
  - · OA equipment · Audio visual equipment · Home appliances
  - · Telecommunication equipment (Terminal) · Measuring equipment
  - · Tooling machines · Computers
  - If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.
- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as;
  - · Transportation control and safety equipment (aircraft, train, automobile etc.)
  - · Traffic signals · Gas leakage sensor breakers · Rescue and security equipment
  - · Other safety equipment etc.
- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as;
  - · Space equipment · Telecommunication equipment (for trunk lines)
  - · Nuclear power control equipment · Medical equipment etc.
- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.
- 3. Please contact and consult with a Sharp sales representative for any questions about this product.

1. Application

This specification applies to the outline and characteristics of OPIC photocoupler Model No. P

2. Outline Refer to the attached sheet, page 3.

3. Ratings and characteristics

Refer to the attached sheet, page 4 to 5.

4. Reliability

Refer to the attached sheet, page 6.

5. Outgoing inspection

Refer to the attached sheet, page 7.

6. Supplement

6.1 Isolation voltage shall be measured in the following method.

- Short between pins 1 and 3 on the primary side and between pins 4, 5 and 6 on the secondary side.
- (2) The dielectric withstand tester with zero-cross circuit shall be used.
- (3) The wave form of applied voltage shall be a sine wave.

#### 6.2 Business dealing name

("O" mark indicates business dealing name of ordered product)

<u> </u>		
Product	Business dealing name	Remark
	PC410LENIP	
	PC410LEYIP	Applied to product as a option (Attachment-2-1 to 2-3.)

6.3 Package specification

Refer to the attached sheet, page 8, 9.

6.4 This Model is approved by UL.

Approved Model No.: PC410L

UL file No.: E64380

6.5 This product is not designed against irradiation.

This product is operated with electrical input and output.

This product incorporates non-coherent light emitting diode.

6.6 ODS materials

This product shall not contain the following materials.

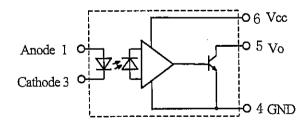
Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methyl chloroform)

6.7 Brominated flame retardants

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this device at all.

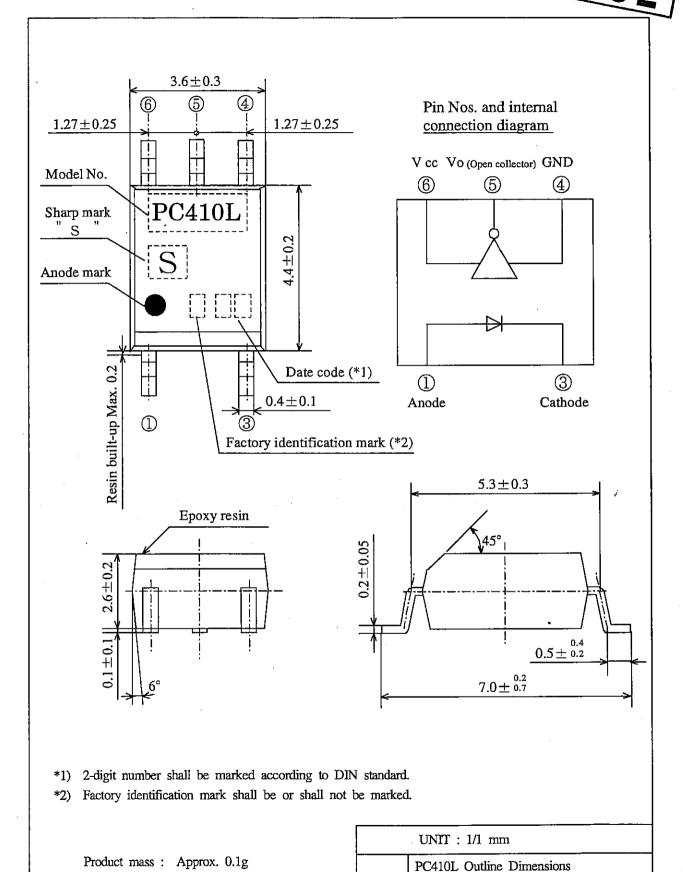
The block diagram 6.8



7. Notes

Refer to the attachment-1-1, 2 (Precautions for Photocouplers).

#### 2. Outline



Name

(Business dealing name: PC410LENIP)

# REFERENC PC410LENIP November 7, 2002

#### 3. Ratings and characteristics

#### 3.1 Absolute maximum ratings

Parameter		Symbol	Rating	Unit	
	*1	Forward current	I <sub>F</sub>	20	mA
Input		Reverse voltage	$V_{R}$	5	V
		Power dissipation	P	40	mW
		Supply voltage	Vcc	7	V
O-44		High level output voltage	V <sub>OH</sub>	7	v
Output		Low level output current	$I_{OL}$	50	mA
	*2	Output collector power dissipation	Po	85 .	mW
	*3	Isolation voltage	Viso(rms)	3.75	kV
		Operating temperature	Topr	-40 to +85	℃
		Storage temperature	Tstg	-40 to +125	℃
	*4	Soldering temperature	Tsol	270	℃

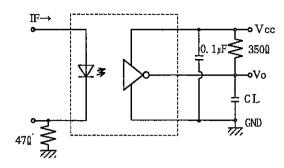
- \*1 The derating factors of forward current vs. ambient temperature are shown in Fig. 3.
- \*2 The derating factors of output collector power dissipation due to ambient temperature are shown in Fig. 4.
- \*3 AC for 1 min, 40 to 60%RH
- \*4 For 10 s or less, 0.2mm or more from lead base.

#### 3.2 Electro-optical characteristics

(Ta=40 to +85°C unless otherwise specified.)

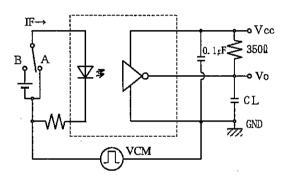
ب. د	1.2 Electro-optical characteristics (1a-40 to 405 C timess outerwise speciment)								
		Parameter	Symbol	Condit	MIN.	TYP.	MAX.	Unit	
		Forward voltage	$V_{\rm F}$	Ta=25°C, I <sub>F</sub> =10mA	1.4	1.6	1.9	V	
Input		Reverse current	$I_R$	_				10	$\mu$ A
		Terminal capacitance	Ct	Ta=25°C, V=0V, f=		60	150	pF	
		Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> =13mA, Vcc=5.	5V, I <sub>F</sub> =5mA	_	0.4	0.6	V
Output		High level output current	I <sub>OH</sub>	Vcc=Vo=5.5V, I <sub>F</sub> =2	250 μ Α	-	0.02	100	$\mu A$
🗟		Low level supply current	Iccl	Vcc=5.5V, I <sub>F</sub> =10m.	A		7	13	mA
		High level supply current	I <sub>CCH</sub>	Vcc=5.5V, I <sub>F</sub> =0mA		-	5	10	mA
		"H-L" threshold input current	I <sub>FHL</sub>	Vcc=5V, R <sub>L</sub> =350 Ω	2,Vo=0.6V		2.5	5	mA
		Isolation resistance	R <sub>ISO</sub>	Ta=25°C, DC=500	V, 40 to 60%RH	5×10 <sup>10</sup>	10 <sup>11</sup>	-	Ω
'		Floating capacitance	Cf	Ta=25°C, V=0V, f=1MHz		-	0.6	_	рF
		"H→L" propagation time	t <sub>PHI</sub> _	Ta=25℃ Vcc=5V,		25	48	75	
3	time	"L→H" propagation time	t <sub>PLH</sub>			25	50	75	
isi	se t	Fall time	tf_	I <sub>F</sub> =7.5mA,		-	10	•	ns
acte	Response	Rise time	tr	$R_L=350\Omega$ ,			20		110
Transfer characteristics	Re	Distortion of pulse width   tphL-tpLH	Δtw	C <sub>L</sub> =15pF, (Refer to Fig. 1)		-	-	35	
Transf	IR.	Instantaneous common mode rejection voltage (High level output)	CM <sub>H</sub>	I <sub>F</sub> =0mA Vo(MIN)=2V	Vcc=5V $V_{CM}=1kV_{(P-P)}$ $R_{L}=350\Omega$	10	20	-	kV/μs
GMR		Instantaneous common mode rejection voltage (Low level output)	CM <sub>L</sub>	I <sub>F</sub> =5mA Vo(MAX)=0.8V	$R_L=350\Omega$ $Ta=25^{\circ}C$ (Refer to Fig. 2)	-10	-20	-	κνιμs

Note) All typical values are at Ta=25°C, Vcc=5V.

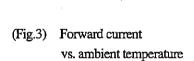


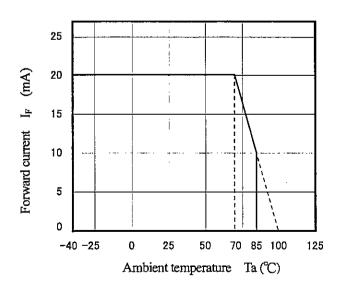
CL contains probe and wiring capacity.

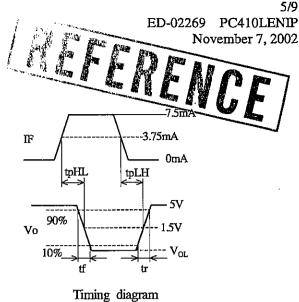
Fig.2 CM<sub>H</sub>, CM<sub>L</sub> test circuit

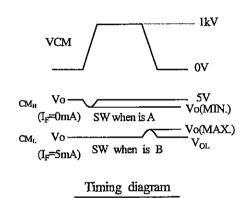


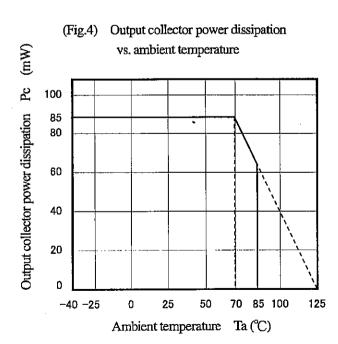
CL contains probe and wiring capacity.











#### ED-02269 PC410LENIP November 7, 2002

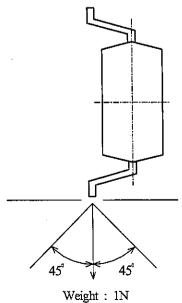
LTPD: 10 or 20

#### 4. Reliability

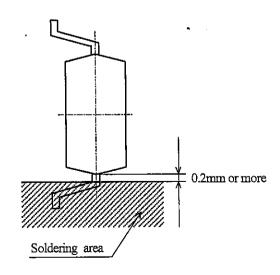
The reliability of products shall satisfy items listed below.

			Samples (n)
Test Items	Test Conditions *1	Failure Judgement Criteria	Defective(C)
Solderability *2	245±2°C, 3 s		n=11, C=0
Soldering heat *3	270°C, 10 s		n=11, C=0
Terminal strength (Bending) *4	Weight: 1N 1 time/each terminal		n=11, C=0
Mechanical shock	15km/s², 0.5ms 3 times/±X, ±Y, ±Z direction	V <sub>F</sub> >U×1.2	n=11, C=0
Variable frequency vibration	200m/s <sup>2</sup> 100 to 2000 to 100Hz/4min. 4 times/ X, Y, Z direction	$\begin{array}{c c} I_R & >U\times 2 \\ I_{OH} & >U\times 2 \\ I_{CCL} & >U\times 1.2 \end{array}$	n=11, C=0
Temperature cycling	1 cycle -40°C to +125°C (30min.) (30min.) 20 cycles test	$\begin{array}{c} I_{CCH} > U \times 1.2 \\ I_{FHL} > U \times 1.3 \\ V_{OL} > U \times 1.2 \end{array}$	n=22,C=0
High temp. and high humidity storage *5	+85°C, 85%RH, 500h	U: Upper specification limit	n=22,C=0
High temp. storage	+125°C, 1000h	L: Lower specification limit	n=22,C=0
Low temp. storage	-40°C, 1000h		n=22,C=0
Operation life	$I_F$ =20mA, Vcc=5.5V $R_L$ =350 Ω, Ta=25°C, 1000h		n=22,C=0

- \*1 Test method, conforms to EIAJ ED 4701.
- \*2 Solder shall adhere at the area of 95% or more of immersed portion of lead, and pin hole or other holes shall not be concentrated on one portion.
- \*3 The lead pin depth dipped into solder shall be 0.2mm away from the root of lead pins. (Refer to the below)
- \*4 Terminal bending direction is shown below.
- \*5 It is evaluated after washing by specified solvent in attached solvent in attachment-1-1.







#### 5. Outgoing inspection

- 5.1 Inspection items
- (1) Electrical characteristics  $V_{F},\,I_{R},\,V_{OL},\,I_{OH},\,I_{CCL},\,I_{CCH},\,I_{FHL},\,R_{ISO},\,Viso$
- (2) Appearance
- 5.2 Sampling method and Inspection level
   A single sampling plan, normal inspection level II based on ISO 2859 is applied.
   The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.065
Minor defect	Appearance defect except the above mentioned.	0.25

#### 6.3 Package specifications

#### 6.3.1 Taping conditions

- (1) Tape structure and Dimensions (Refer to the attached sheet, Page 8)
  The carrier tape has the heat pressed structure of A-PET material carries tape of protect against static electricity and three layers cover tape (PET material base).
- (2) Reel structure and Dimensions (Refer to the attached sheet, Page 9)

  The taping reel shall be of plastic with its dimensions as shown in the attached drawing.
- (3) Direction of product insertion (Refer to the attached sheet, Page 9)
  Product direction in carrier tape shall direct to the anode mark at the hole side on the tape.
- (4) Joint of tape

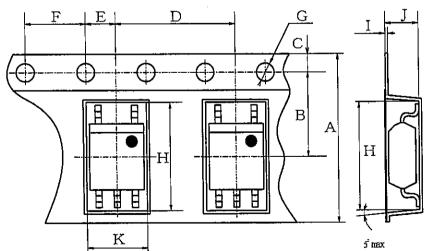
  The cover tape and carrier tape in one reel shall be jointless.
- (5) The way to repair taped failure devices

  The way to repair taped failure devices cut a bottom of carrier tape with a cutter, and after replacing to good devices, the cut portion shall be sealed with adhesive tape.

#### 6.3.2 Adhesiveness of cover tape

- The exfoliation force between carrier tape and cover tape shall be 0.2N to 0.7N for the angle from  $160^\circ$  to  $180^\circ$ .
- 6.3.3 Rolling method and quantity
  - Wind the tape back on the reel so that the cover tape will be outside the tape.
     Attach more than 20cm of blank tape to the trailer and the leader of the tape and fix the both ends with adhesive tape. One reel shall contain 3000pcs.
- 6.3.4 Outer packing appearance (Refer to attached sheet, Page 9)
- 6.3.5 Marking
  - The outer packaging case shall be marked with following information.
    - \* Model No. \* Number of pieces delivered \* Production date
- 6.3.6 Storage condition
  - Taped products shall be stored at the temperature 5 to 30°C and the humidities lower than 70%RH.
- 6.3.7 Safety protection during shipping
  - · There shall be no deformation of component or degradation of electrical characteristics due to shipping.

#### Carrier tape structure and Dimensions

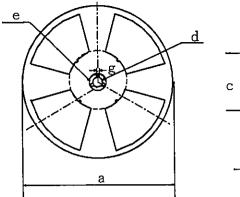


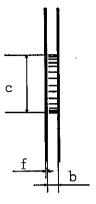
Dimensions list (Unit: mm)

111	TOTISTOTIS III	a. (∪	me . mmi								
	A	В	С	D	E	F	G	H	I	J	K
	±0.3	±0.05 5.5	±0.1	±0.1 8.0	±0.1	±0.1	+0.1 -0.0 φ1.5	±0.1 7.4	±0.05	±0.1 3.1	±0.1 4.0

## November 7, 2002

#### Reel structure and Dimensions

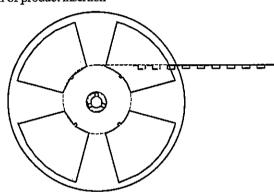




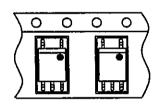
Dimensions list	(Unit:mm)
-----------------	-----------

a	Ъ	С	d
370	13.5±1.5	80±1.0	13±0.5
е	f	g	
21±1.0	2.0±0.5	2.0±0.5	

#### Direction of product insertion

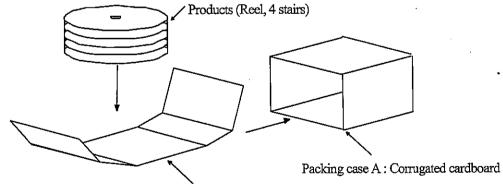






#### Outer packing appearance

- (1) Carrier tape with 3,000pcs. of the devices (reeled) are packed in packing case.
- (2) The packing case is sealed by kraft tape & the label is placed on it. (Max. 4 reels are packed in one carton. (Max. 12,000pcs. of devices are in one carton.))



Packing case B: Corrugated cardboard

(380)(85) Label: Paper (375)Printed Model No., (Business dealing name), Kraft tape Quantity, production date

Regular packing mass: 3kg ( ): Reference dimensions

(Unit:mm)



#### 1. Recommended operating conditions

Parameter	Symbol	MIN.	MAX.	Unit
Low level input current	$I_{FL}$	0	250	μΑ
High level input current	I <sub>FH</sub>	8	15	mA
Supply voltage	Vcc	4.5	5.5	V
Fan out (TTL load)	N	-	5	-
Operating temperature	Topr	-40	+85	°C

#### 2. For cleaning

(1) Solvent cleaning: Solvent temperature 45°C or less

Immersion for 3 min or less

(2) Ultrasonic cleaning: The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc.

Please test it in actual using condition

and confirm that doesn't occur any defect before starting the ultrasonic cleaning.

(3) Applicable solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

When the other solvent is used, there are cases that the packaging resin is eroded.

Please use the other solvent after thorough confirmation is performed in actual using condition.

#### 3. Precaution for use

Transistor of detector side in bipolar configuration is apt to be affected by static electricity for its minute design. When handling them, general counterpane against static electricity should be taken to avoid breakdown of devices or degradation of characteristics.

#### 4. Caution the circuit design

- 4.1 In order to stabilize power supply line, we should certainly recommend to connect a by-pass capacitor of 0.01  $\mu$ F or more between Vcc and GND near the device.
- 4.2 When steep voltage noise is applied between the primary side and the secondary side of the photocoupler, current flows or changes in the light emitting diode through a parasitic capacitance between the primary side and the secondary side of the photocoupler, then there is a case that miss operation occurs depending upon the applied noise level.
  We should certainly recommend to use a by-pass capacitor between both terminals of the light emitting diode where used in a noisy environment.
- 4.3 The detector which is used in this device, has parasitic diode between each pins and GND.
  There are cases that miss operation or destruction possibly may be occurred if electric potential of any pin becomes below GND level even for instant.

Therefore it shall be recommended to design the circuit that electric potential of any pin does not become below GND level.

4.4 The LED used in the Photocoupler generally decreases the light emission power by operation.
In case of long operation time, please design the circuit with considering the decreases of the light emission power of the LED.
(50%/5years) Please decide the input current which become 2 times of MAX. I<sub>FHL</sub>.



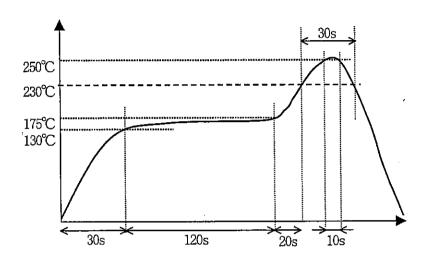
#### 5. Precautions for Soldering Photocouplers

(1) In the case of flow soldering (Whole device dipping)

It is recommended that flow solder be at 270°C and within 6 seconds (Pre-heating: 100 to 105°C, 30±5 seconds).

#### (2) If solder reflow:

It is recommended that soldering be done at the temperature and the time within the temperature profile as shown in the figure below. (2 times or less)



#### (3) Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin.

So keep the package temperature within that specified in Item (1). Also avoid immersing the resin part in the solder.

1. This specification shall be applied to photocoupler, Model No. PC410L as an option.

2. Applicable Models (Business dealing name)

PC410LEYIP

3. The relevant models are the models Approved by VDE according to DIN VDE0884.

Approved Model No.: PC410L

VDE approved No.: 5911ÜG (According to the specification DIN VDE0884/08.87)

Operating isolation voltage U<sub>IORM (Peak)</sub>: 570V

• Transient voltage UTR(Peak) : 4000V

• Pollution: 2 (According to VDE0110/01.89)

• Clearances distance (Between input and output): 4.0mm (MIN.)

Creepage distance (Between input and output): 4.0mm (MIN.)

• Tracking-proof: CTI 175 (Material group IIIa: VDE0110/01.89)

· Safety limit values

Current (Isi): 120mA (Diode side)

Power (Psi): 240mW (Phototransistor side)

Temperature (Tsi): 150°C

In order to keep safety electric isolation of photocoupler, please set the protective circuit to keep within safety limit values when the actual application equipment troubled.

· Indication of VDE approval prints "

VDE-Reg. -Nr. 5911 " on packagé.

4. Outline

Refer to the attachment-2-2.

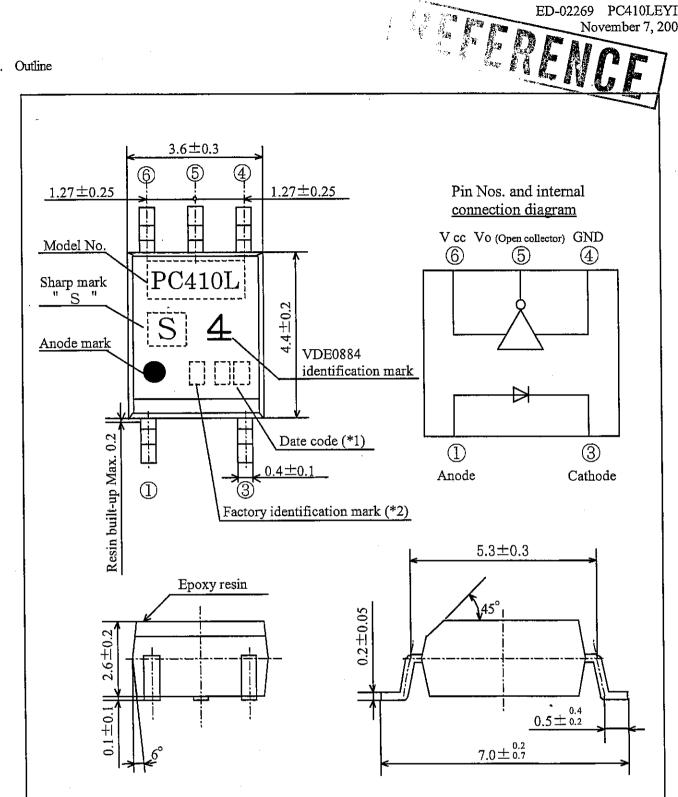
5. Isolation specification according to VDE 0884

	Parameter	Symbol	Condition	Rating	Unit	Remark
Cla	ss of environmental test	••	DIN IEC68	40/85/21	•	
Pol	lution	_	DIN VDE0110	2		
Ma	ximum operating isolation voltage	U <sub>IORM(PEAK)</sub>	<u>-</u>	570	V	
Par	tial discharge test voltage (Between input and output)					Refer to
	Diagram 1	T 1	tp=60s, qc<5pC	684	V	the Diagram 1,2
İ	Diagram 2	Upr <sub>(PEAK)</sub>	tp=1s, qc<5pC	912	V	(Attachement-2-3)
Ma	ximum over-voltage	U <sub>INITIAL(PEAK)</sub>	t <sub>INI</sub> =10s	4000	V	
Saf	Pety maximum ratings					D-64-
	1) Case temperature	Tsi	I <sub>F</sub> =0, P <sub>C</sub> =0	150	ပ္	Refer to Fig. 6,7
	2) Input current	Isi	Pc=0	120	`mA	(Attachement-2-3)
	3) Electric power (Output or Total power dissipation)	Psi		240	mW	(7 Killionomeric 2 3)
_			Ta=Tsi	MIN.10 <sup>9</sup>		
ı	lation resistance	R <sub>ISO</sub>	Ta=Topr (MAX.)	MIN.10 <sup>11</sup>	Ω	
(16	est voltage between input and output; DC500V)	put and output; DCS00V)  Ta=25°C MIN.10 <sup>12</sup>				

#### 6. Precautions in performing isolation test

- 6.1 Partial discharge test methods shall be the ones according to the specifications of VDE 0884/08.87
- 6.2 Please don't carry out isolation test (Viso) over U<sub>INITIAL</sub>.
  This product deteriorates isolation characteristics by partial discharge due to applying high voltage (ex. U<sub>INITIAL</sub>).
  And there is possibility that this product occurs partial discharge in operating isolation voltage. (U<sub>IORM</sub>).

#### 2. Outline



- (\*1) 2-digit number shall be marked according to DIN standard.
- (\*2) Factory identification mark shall be or shall not be marked.

Product mass: Applox. 0.1g

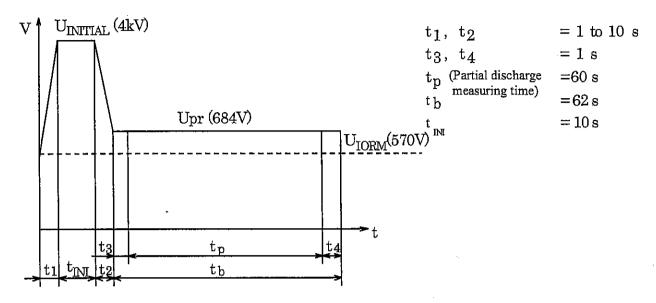
UNIT: 1/1mm

Name

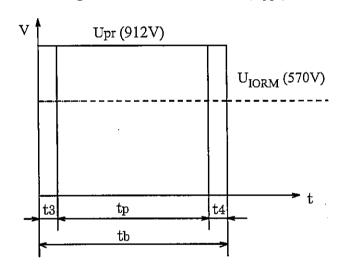
PC410L Outline Dimensions (Business dealing name: PC410LEYIP)

# November 7, 200

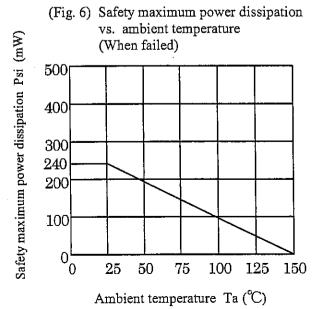
Method of Diagram 1: Breakdown test (Apply to tape test and sampling test)

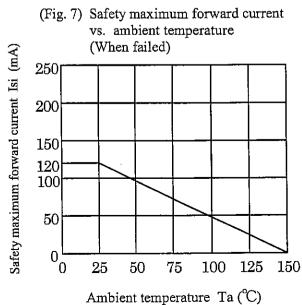


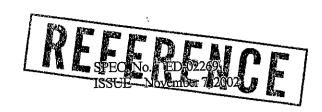
Method of Diagram 2: Non breakdown test (Apply to all device test)



t3, t4	=0.1 s
tp (Partial discharge	=1 s
tb measuring time)	=1.2 s







# SHARP

#### OPTO-ELECTRONIC DEVICES DIVISION ELECTRONIC COMPONENTS GROUP SHARP CORPORATION

# **SPECIFICATION**

DEVICE SPE	CIFICATION FOR	
	PHOTOCOUPL	ER .
MODEL'No.		
	PC410L	
		D daling name
<u> </u>	Business dealing name PC410LENIP	Business dealing name PC410LEYIP
<u> </u>	10-10-22-01	
Specified for		
	<u></u>	
	•	
er confirmation of the napproving signature	e contents, please be sure to ser	consists of 15 pages including cover.  Id back copies of the Specifications
er confirmation of the approving signature	e contents, please be sure to ser	d back copies of the Specifications
er confirmation of the approving signature	e contents, please be sure to ser	d back copies of the Specifications
er confirmation of the	e contents, please be sure to ser	d back copies of the Specifications
er confirmation of the	e contents, please be sure to ser	d back copies of the Specifications
approving signature	e contents, please be sure to sen	d back copies of the Specifications  PRESENTED
er confirmation of the approving signature approximate approxi	e contents, please be sure to sen	d back copies of the Specifications
approving signature	e contents, please be sure to sen	copies of the specifications  PRESENTED
approving signature	e contents, please be sure to sen	d back copies of the Specifications
approving signature	e contents, please be sure to sen	copies of the specifications  PRESENTED
approving signature	e contents, please be sure to sen	copies of the specifications  PRESENTED
approving signature STOMER'S APPRO	e contents, please be sure to sen	PRESENTED  DATE  BY  1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1
approving signature STOMER'S APPRO	e contents, please be sure to sen	PRESENTED  DATE
approving signature STOMER'S APPRO	e contents, please be sure to sen	PRESENTED  DATE  BY  K. Hachimura,  Department General Manager of Engineering Dept., II
approving signature STOMER'S APPRO	e contents, please be sure to sen	PRESENTED  DATE  BY  M. Hachimura,  Department General Manager of